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(54) **TEMPERATURE LOAD MANAGEMENT DEVICE, TEMPERATURE LOAD MANAGEMENT METHOD, AND COMPUTER PROGRAM**

(57) A temperature load management device (20) is for use in exposing a user to a second environment for removing a first temperature load accumulated in a first environment. The temperature load management device (20) includes the control unit (10) as a main component. The control unit (10) controls the second environment or makes a notification of a time to end the exposing of the user to the second environment, based on physiological information on the user.

FIG.12

